DECLARATION FOR PATENT

As a below named inventor, I/we hereby declare that: my residence, post office address and citizenship are as stated below next to my name; I/we believe I/we am/are the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

ORGANOMETALLIC TRANSITION METAL COMPOUND, BISCYCLOPENTA-DIENYL LIGAND SYSTEM, CATALYST SYSTEM AND PROCESS FOR PREPARING POLYOLEFINS

the specifica	ation of which: (check one)
. []	is attached hereto
	OR
[X]	was filed on (MM/DD/YYYY) 11/02/2004, as United States Application Number or
PCT Interna	tional Application Number PCT/EP2004/12358 and was amended on (MM/DD/YYYY) (if applicable).

I/we hereby state that I/we have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above; and I/we acknowledge the duty to disclose information which is material to the patentability of this application as defined in 37 CFR §1.56, including for continuation-in-part applications, material information which became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

I/we hereby claim foreign priority benefits under 35 USC §119(a) – (d) or (f), or § 365(b) of any foreign application(s) for patent or inventor's certificate, or §365(a) of any PCT international application which designated at least one country other than the United States of America, listed below and have also identified below, by checking the box below, any foreign application for patent or inventor's certificate, or of any PCT international application having a filing date before that of the application on which priority is claimed:

Pi	rior Foreign App	lication(s)	Priority	Claimed
Number	Country	Month/Day/Year Filed	Yes	No
10352139.9	DE	11/04/2003	X	

I/we hereby claim the benefit under 35 USC §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by 35 USC §112, first paragraph, I/we acknowledge the duty to disclose material information as defined in 37 CFR §1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

U.S. Application Serial No.	Filing Date	Status

I/we hereby claim the benefit under 35 USC §119(e) of any United States provisional application(s) listed below:

Application Serial No.	Filing Date:
60/528591	12/11/2003

Send correspondence to:

CUSTOMER NUMBER 34872

Direct telephone calls to:

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I/we hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Sec. 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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